COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE | BOARD #: PMP20612 | REV #: A | SUN REV #: Not In VersionControl
T10 #: N/A

PLOT NAME = Top Assembly Drawing | GENERATED: 12/21/2016 4:58:57 PM | TEXAS INSTRUMENTS
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: DOI

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP20612</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td>TID #:</td>
<td>N/A</td>
<td></td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 12/21/2016 4:50:59 PM</td>
<td>TEXAS INSTRUMENTS</td>
<td></td>
</tr>
</tbody>
</table>
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